Interconnect Task Group Update – Package Modeling

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Package and On-Die Interconnect Modeling

Where we started 3 months ago (Walter Katz's DesignCon IBIS Summit presentation describing what interconnect to model in the .ibs file):

Decisions Made	In .ibs	In EMD
Connectors	No	Yes
Cables	No	Yes
Broadband EBD	No	Yes
MCM	No	Yes
Interposers	No	Yes
3-D structures	No	Yes
Stacked Memory	No	Yes
Splits/Joins of Signal (I/O) in Package or Die	No	Yes
RDL as separate element	No	Yes
New list of supply (PDN) die pads	Yes	Yes
Separate package and on-die interconnect model	Yes	Yes
Package model can include on-die model	Yes	Yes
Broadband I/O Package Modeling	Yes	Yes
Package PDN	Yes	Yes
Broadband I/O On-Die Modeling	Yes	Yes
On-Die PDN	Yes	Yes
Interconnect coupling (crosstalk) between I/O and I/O	Yes	Yes
Interconnect coupling between I/O and PDN	Yes	Yes
Optical Interconnect	No	No



Interconnect Task Group Progress February – April 2014

Two proposals presented and debated

- SiSoft proposal creates new keywords under [Define Package Model]
- Mentor/Cadence proposal expands capabilities of [External Circuit]

Each proposal created syntax examples covering package model formats requested by Micron and others (S-parameter and IBIS-ISS)

- Signal connections from pin to buffer (may include on-die interconnect)
- Power connecting from multiple pins to all buffers (no on-die interconnect)
- Power connecting from pins to individual buffers (includes on-die PDN)
- Generic 2 and 4-port signal models connecting to all [Model]s

Proposals were voted on in the April 30 meeting

The task group will focus on developing the SiSoft proposal



Proposal Details

Current BIRD proposal draft found at:

http://www.eda.org/ibis/interconnect_wip/PackageBIRD_3.docx

IBIS package modeling is enhanced to support broadband and coupled package and on-die interconnect using IBIS-ISS and Touchstone models

[ISS Model Data] begins new section under [Define Package Model] [Begin ISS Model] defines a unique model name

- This section contains all the model data and can reference external files
- Subparameters defined so far include:
 - Language, File, Subckt, Parameter, Unused_Port_Termination,
 Number_of_Ports, Port
- * All keyword and subparameter names subject to change



Proposal Details - Ports

The Ports subparameter defines information on each port (or terminal) of an IBIS-ISS subckt (or Touchstone) file

Port <Field 1><Field 2><Field 3><Field 4>{<Field 5><Field 6><Field 7>}

- Field 1: port number
- Field 2: describes if port is at the pin, die pad or buffer
- Field 3: Pin_name, Signal_name, Model_name or Default
- Field 4: valid Pin, Signal or Model name, or NA if Default in Field 3
- Field 5: Optionally used as Diff_pos, Diff_neg or SE if Field 3 is
 Model_name or to indicate connection as a buffer supply terminal
- Field 6: Channel number used with defining victim/aggressor for xtalk
- Field 7: Aggressor or NA, defines xtalk modes



Ports Examples

Port 1 Pin	Pin name	M8	NA	NA	NA

Port 1 Pin Pin_name M8

Port 1 Pad Pin_name M8

Port 1 Buffer Pin_name M8

Port 1 Buffer Pin_name M8 Pullup_Reference

Port 1 Pin Model_name DQ

Port 1 Pin Model_name DQS Diff_pos

Port 1 Pin Default NA SE

Port 1 Pin Model name DQ SE

Port 1 Buffer Pin_name M8 NA 2

Port 1 Buffer Pin_name M8 NA 3 Aggressor

Port 1 Buffer Signal_name VDDQ



Syntax Examples – Single Nets

S-Parameter vs. IBIS-ISS

[Define Package Model]

[ISS Model Data]

[Begin ISS Model] IOA3

Language Touchstone

File Value ioA3.s2p

Number_of_Ports 2

Port 1 Pin Pin_name A3

Port 2 Buffer Pin_name A3

[End ISS Model]

[End ISS Model Data]

[End Package Model]

[Begin ISS Model] IOA3

Language IBIS_ISS

File Value io.iss

Subckt io

Parameter Length Value 10.0 | 10mm

Number_of_Ports 2

Port 1 Pin Pin_name A3

Port 2 Buffer Pin name A3

[End ISS Model]



Syntax Example – Generic Differential Package

```
[Begin ISS Model] DQS
```

Language Touchstone

File Value DQS.s4p

Number_of_Ports 4

Port 1 Pin Model name DQS Diff pos

Port 2 Buffer Model_name DQS Diff_pos

Port 3 Pin Model_name DQS Diff_neg

Port 4 Buffer Model name DQS Diff neg

[End ISS Model]



Syntax Example – Victim Net With Agressors

```
[Begin ISS Model] IOA3
Language Touchstone
File Value ioA3.s10p
Number of Ports 10
Port 1 Pin
              Pin name
                          A3
Port 2 Buffer
                          A3
              Pin name
Port 3 Pin
              Model name DQ NA
                                      1 Aggressor
Port 4 Buffer
              Model name DQ NA
                                      1 Aggressor
Port 5 Pin
              Model name DQ NA
                                      2 Aggressor
Port 6 Buffer
              Model name DQ NA
                                      2 Aggressor
Port 7 Pin
              Model_name DQS Diff_pos 3 Aggressor
Port 8 Buffer
              Model name DQS Diff pos 3 Aggressor
Port 9 Pin
              Model name DQS Diff neg 3 Aggressor
Port 10 Buffer
              Model name DQS Diff neg 3 Aggressor
```



[End ISS Model]

Next Steps

Defining model hierarchy

Model precedence similar to [Package], [Pin], [Package Model]
 Refining Unused_Port_Termination subparameter definition
 Are more subparameters needed?
 Will victim/aggressor crosstalk simulations be supported fully?

Co-develop syntax for EBD specification overhaul Complete BIRDs and get them into the next release of IBIS (later this year?)

